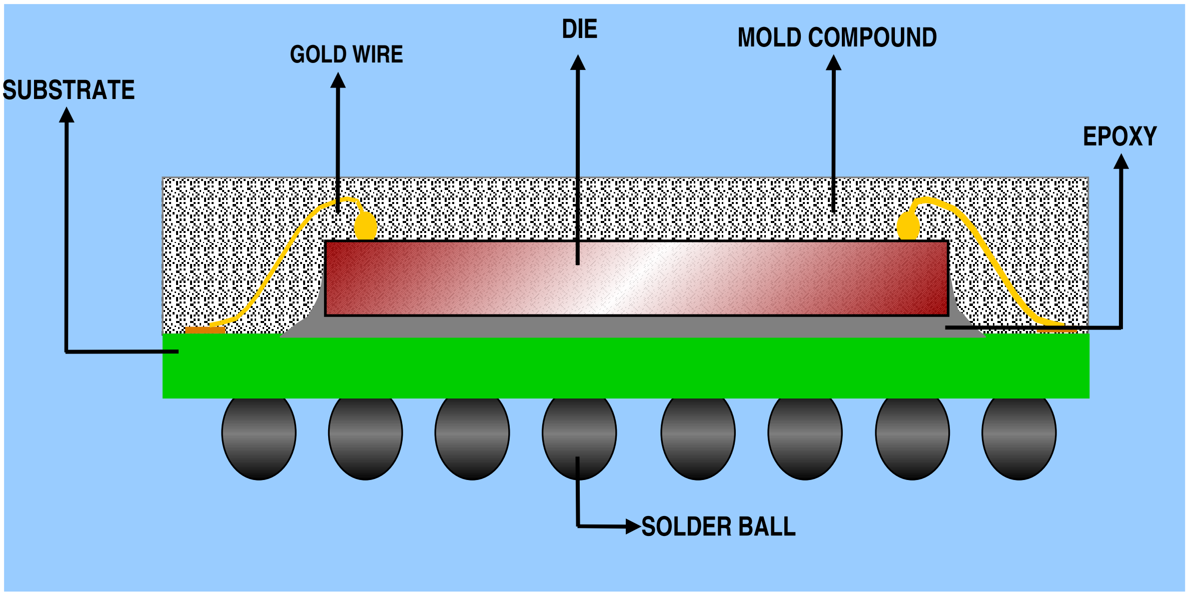

INFORMATION

Package Type	:	49 FBGA
Package Size	:	7 x 7 x 1.45 mm
Device	:	VS1033C-B/LSR-ROHS
Die Size	:	173.20 x 168.60 mils
Epoxy P/N	:	21200044
Epoxy Type	:	Ablebond 2000B (Green)
Substrate	:	1E049071, HL832NX, AUS 308
Cavity Size (DAP)	:	230 x 230 mils
Wire P/N	:	23010045
Wire Diameter	:	25 microns NL51
Number of Wires	:	63 wires
Mold Compound P/N	:	31760189
Mold Compound Type	:	EME G760V (Green)
Solder Ball P/N	:	32180013
Solder Ball Type	:	Sn96.5 Ag3.0 Cu0.5
Solder Ball Diameter	:	0.3048 mm (12 mils)

MATERIAL WEIGHT

Die	:	0.0160 gram
Substrate	:	0.00260 gram
Epoxy	: :	0.0060 gram
Gold Wire	:	0.000755 gram
Mold Compound	:	0.08900 gram
Solder Balls	:	0.01690 gram
Total Weight	**:**	**0.131255 gram**

VLSI Solution Oy